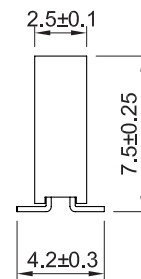
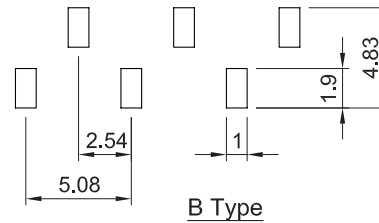
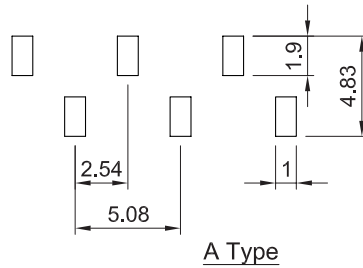


### Recommended P.C. Board SMD Layout



* Contact Plating Option	Full Gold Plating	Gold Plated On Contact Area Tin Plated on Solder Area	Full Tin Plating
	G : Gold Flash G10: Gold 10u" G15: Gold 15u" G30: Gold 30u"	S: Gold Flash S10: Gold 10u" S15: Gold 15u" S30: Gold 30u"	T: Tin 100u"

General Tolerance	
X. ± 0.50	X.° ± 5°
.X ± 0.20	.X° ± 2°
.XX ± 0.10	.XX° ± 1°
Units : mm	

## Specifications

- Current Rating: 3 Amps
- Insulator Resistance: 1000 Megohms min.
- Contact Resistance: 20 m ohms max.
- Dielectric Withstanding: AC 600V
- Operating Temperature: -40°C~+125°C
- Contact Material: Phosphor Bronze
- Insulator Material: Polyester, UL 94V-0, Nylon-6T
- Contact Plated: \*see options below
- Standard: Full Gold Flash

## Part Numbering System

**FHC-H7.1W2.5T4.2SS X - XX - X X X X**

- Series** \_\_\_\_\_
- Pin Type Option:** \_\_\_\_\_  
A = A Type  
B = B Type
- No. of Contact:** \_\_\_\_\_
- Contact Plating:** \_\_\_\_\_
- Cap Option:** \_\_\_\_\_  
Nil = No Cap  
F = Film  
M = Metal  
P = Plastic
- Packing Method:** \_\_\_\_\_  
B = Tube  
T = Tape & Reel
- Insulator Material:** \_\_\_\_\_  
N = High Temperature Nylon-6T